

AMENDMENTS TO THE SPECIFICATION:

After the title, please insert the following:

Cross-Reference to Related Applications

This application is a divisional of U.S. patent application number 09/655,787, filed September 6, 2000, which is a continuation of international application number PCT/JP99/05676, filed October 14, 1999 and claims the benefit of Japanese application number 10-291867, filed October 14, 1998. The content of all three applications is incorporated herein by reference.

Please substitute the following paragraph for the paragraph located at page 4, lines 30-34:

To attain the above-mentioned object, the invention is characterized in comprising a step of cleaning a surface of an object to be processed by using ClF_3 gas; and removing chlorine derived from the ClF_3 gas still remaining on the surface of the object under treatment even after the step of cleaning the surface.

Please substitute the following paragraph for the paragraph located at page 4, lines 35-37:

The invention is characterized in that the step of removing chlorine includes a step of removing chlorine from the surface of the object to be processed by using a reducing gas.

Please substitute the following paragraph for the paragraph located at page 5,
lines 1-2:

The invention is characterized in that the reducing gas is H_2 gas.

Please substitute the following paragraph for the paragraph located at page 5,
lines 3-9:

The invention is characterized in comprising the steps of making ClF_3 gas adhere to a surface of an object to be processed by supplying the ClF_3 gas to the surface of the object to be processed; interrupting the supply of the ClF_3 gas to the surface of the object to be processed; and cleaning the surface of the object to be processed by using the ClF_3 gas adhering to the surface of the object to be processed.

Please substitute the following paragraph for the paragraph located at page 5,
lines 10-12:

The invention is characterized in that the object to be processed is cooled to $20^{\circ}C$ or below in the step of making ClF_3 gas adhere to the surface of the object.

Please substitute the following paragraph for the paragraph located at page 5,
lines 13-18:

The invention is characterized in comprising a processing vessel in which an object to be processed is placed; a means for supplying a ClF_3 gas into the processing

vessel; a means for activating the ClF_3 gas supplied in the processing vessel; and a means for supplying a reducing gas into the processing vessel.

Please substitute the following paragraph for the paragraph located at page 5, lines 19-24:

The invention is characterized in comprising a processing vessel in which an object to be processed is placed; a means for supplying ClF_3 gas into the processing vessel; a means for promoting adhesion of ClF_3 gas to the object to be processed; and a means for activating ClF_3 gas supplied in the processing vessel.

Please substitute the following paragraph for the paragraph located at page 5, lines 25-27:

The invention is characterized in further comprising a mount located in the processing vessel to set the object to be processed thereon.

Please substitute the following paragraph for the paragraph located at page 5, lines 28-31:

The invention is characterized in that the means for promoting adhesion of the ClF_3 gas to the object to be processed is provided in the mount to function to cool the object to be processed on the mount.

Please substitute the following paragraph for the paragraph located at page 5, lines 32-35:

The invention is characterized in that the means for activating the ClF_3 gas heats the object to be processed in a heating position distant from the object setting position for setting the object on the mount.

Please substitute the following paragraph for the paragraph located at page 5, lines 36-37, continuing to page 6, line 1:

The invention is characterized in further comprising a means for elevating and lowering the object to be processed between the object setting position and the heating position.

Please substitute the following paragraph for the paragraph located at page 6, lines 2-9:

The invention is characterized in comprising the surface processing apparatus; a transport chamber capable of maintaining a non-reactive atmosphere inside and

capable of transporting an object to be processed in the non-reactive atmosphere to and from the surface processing apparatus; and one or more processing apparatuses capable of transporting the object to be processed to and from the transport chamber.

Please substitute the following paragraph for the paragraph located at page 6, lines 10-12:

The invention is characterized in that the processing apparatus is a metal wiring formation chamber for making metal wiring on the object to be processed.